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Modeling and Simulation of Welding Processes

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Deadline for manuscript submissions: closed (15 December 2022)

Message from the Guest Editors

For this Special Issue "Modeling and Simulation of Welding Processes", papers on advanced welding for laser welding, friction stir welding, electron beam welding, arc welding, and hybrid welding are welcome. Publishing research on the effects of advanced welding on the material for microstructure and performance; development of process parameters for new advanced materials (high entropy alloys, light metal alloys, and dissimilar metals); modeling and simulation of welds process/material interaction, thermal effects, stresses, and distortion; and destructive and non-destructive control. Papers that combine both experimental and theoretical approaches are especially welcomed.

Contributions from around the world will contribute to the success of this Special Issue, which aims at spreading the potential of advanced welding at joining well-established and innovative metallic parts.



mdpi.com/si/128738







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Message from the Editor-in-Chief

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